

PRODUCT NUMBER
SEE TABLE

1

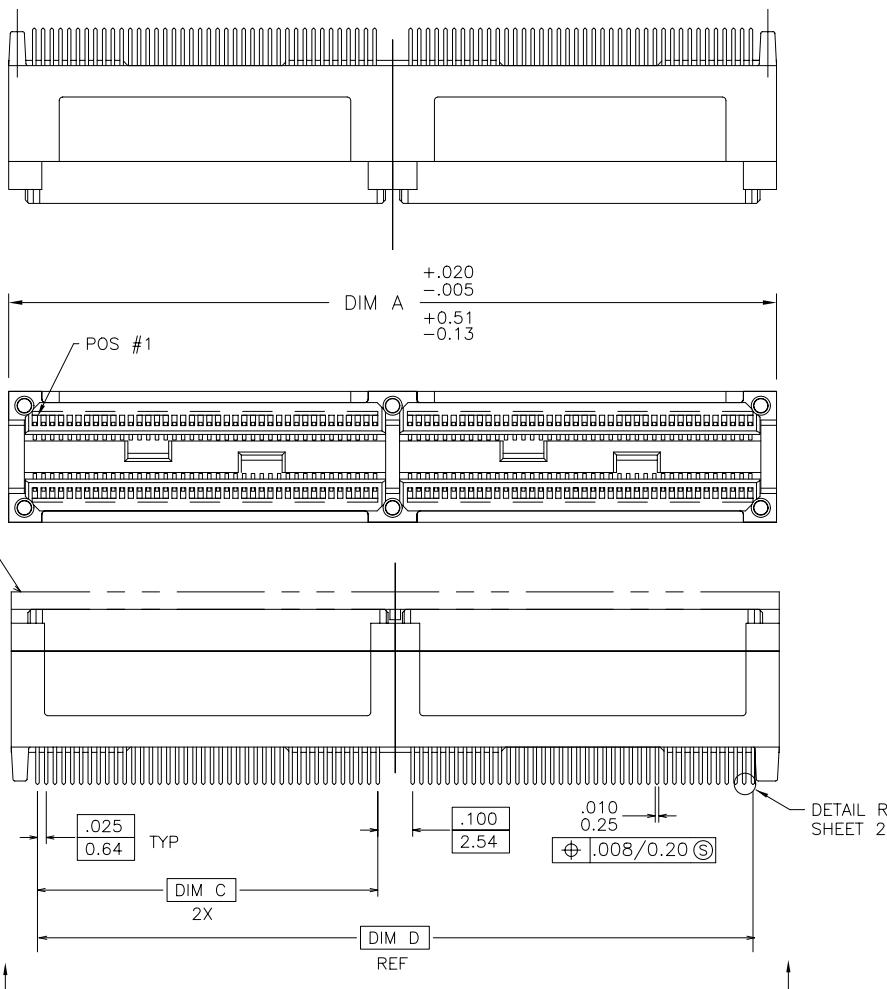
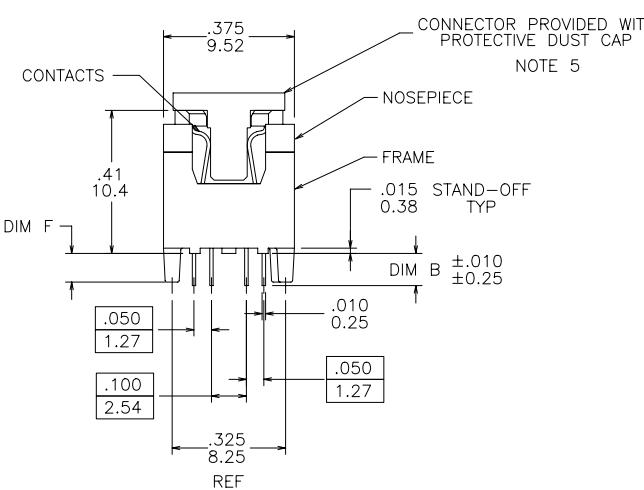
2

3

4

5

6



VIEW K (SHEET 2)

mat'l. code		surface		tolerance	projection	product family
		ISO 1302		ISO 406 ISO 1101		MICROPAX
Itr	ecn no	dr	date	tolerances unless otherwise specified		
H	V32226	MRC	12/23/93	.XX±.01/.3	INCH/MM	
J	V60714	EPK	7/01/96	.XXX±.005/.13		
K	V71714	EPK	7/09/98	0°±2°	scale 2:1	
L	V12115	CRG	8/16/01	dr	L. POTTEIGER	dwg no
M	V20402	MEM	3/08/02	engr	T. LEMKE	sheet 1 of 3
N	M05-0082	MHT	5/05/05	chr	T. LEMKE	size
P	M06-0279	MNR	7/22/06	appd	T. LEMKE	89648
sheet	revision	P	P	P		A3
index	sheet	1	2	3		

form: A3

1

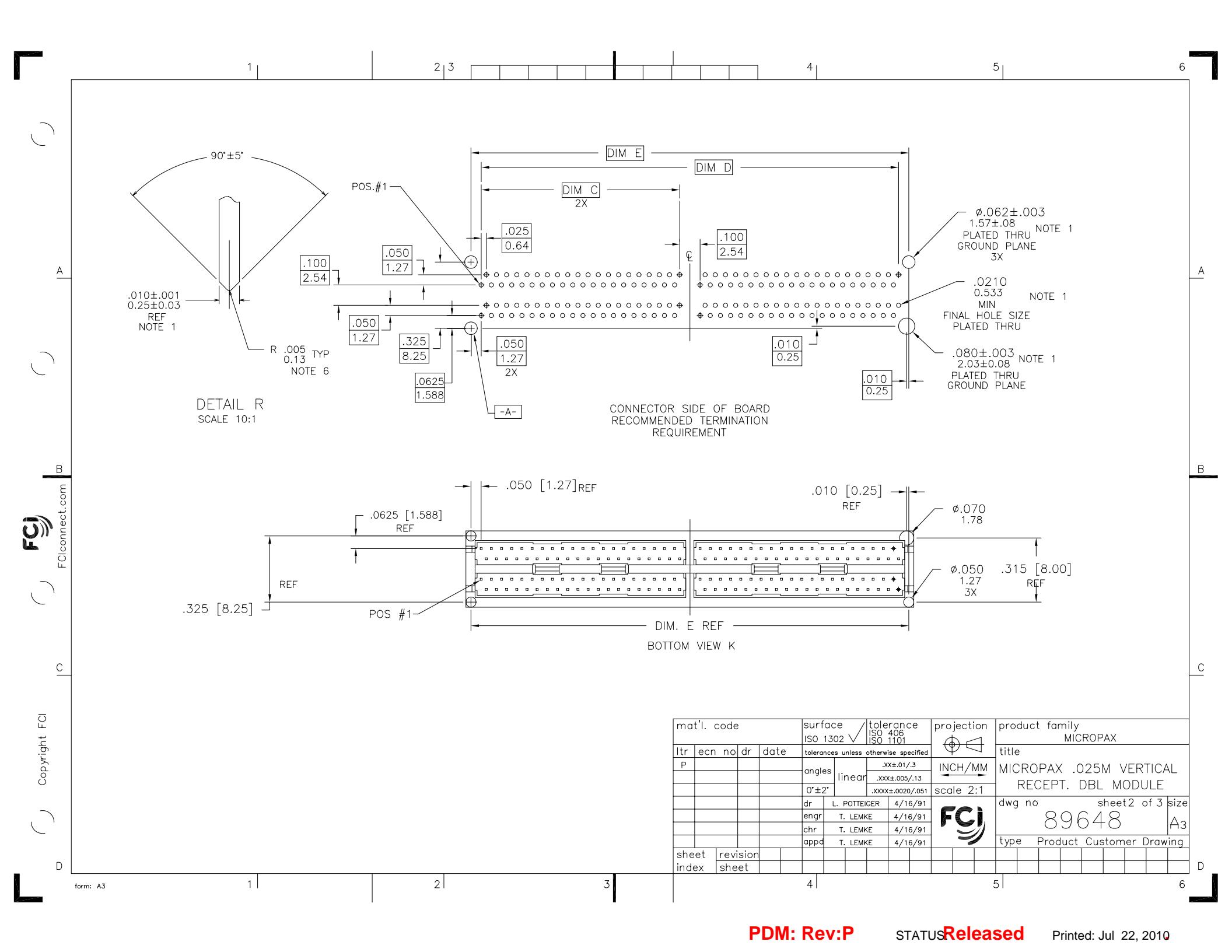
2

3

4

5

6



1	2	3	4	5	6		
PRODUCT NUMBER	NO. OF CONTACTS	DIM A	DIM B	DIM C	DIM D		
89648-001	160	2.200/55.88	.092/2.34	.975/24.76	2.050/52.07		
89648-002			.155/3.94			.144/3.66	.125/3.18
89648-001LF	160	2.200/55.88	.092/2.34	.975/24.76	2.050/52.07		
89648-002LF			.155/3.94			.082/2.08	.062/1.58
					.144/3.66	.125/3.18	NOTE 4

NOTES :

① ALL BOARD HOLES \oplus \emptyset .006/.15 ⑤ A ⑥

② MATERIALS : DIELECTRIC : LCP
CONTACTS : Cu Be
FRAME : ZINC ALLOY #3

③ PLATING : -001
SOLDER TAILS : 150 μ "/3.81um Sn Pb
FRAME : 100 μ "/2.54um NICKEL
CONTACT : 30 μ "/.76um GXT OVER 50 μ "/1.27um Ni

LEAD FREE OPTION:

SOLDER TAILS : 150 μ "/3.81um Sn
FRAME : 100 μ "/2.54um NICKEL
CONTACT : 30 μ "/.76um GXT OVER 50 μ "/1.27um Ni

④ PLATING : -002
SOLDER TAILS : 150 μ "/3.81um Sn Pb
FRAME : 150 μ "/3.81um SnPb
CONTACT : 30 μ "/.76um GXT OVER 50 μ "/1.27um Ni

LEAD FREE OPTION:

SOLDER TAILS : 150 μ "/3.81um Sn
FRAME : 150 μ "/3.81um Sn
CONTACT : 30 μ "/.76um GXT OVER 50 μ "/1.27um Ni

⑤ DO NOT REMOVE PROCESSING CAP UNTIL SOLDERING IS COMPLETED. CAP WILL PREVENT POTENTIAL NOSE PIECE BOW DURING HIGH TEMP. SOLDERING PROCESS.

⑥ .002/.05 MAX BURR PERMITTED.

⑦ PART NUMBERS WITH LF AT THE END ARE LEAD FREE.

8. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 20 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN. SEE APPLICATION NOTE/PROCEDURES IF THEY ARE AVAILABLE.

THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 20 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.5mm MINIMUM THICK CIRCUIT BOARD. SEE APPLICATION NOTES/PROCEDURES IF THEY ARE AVAILABLE

⑨ IF "LF" P/N THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008.

mat'l. code				surface		tolerance	projection	product family
				ISO 1302		ISO 406	ISO 1101	MICROPAX
Itr	ecn	no	dr	date	tolerances unless otherwise specified			title
P					angles	.XX±.01/.3	INCH/MM	MICROPAX .025M VERTICAL
					linear	.XXX±.005/.13		RECEPT. DBL MODULE
					0°±2°	.XXXX±.0020/.051	scale 2:1	
					dr	L. POTTEIGER	4/16/91	
					engr	T. LEMKE	4/16/91	
					chr	T. LEMKE	4/16/91	
					appd	T. LEMKE	4/16/91	
					sheet	revision		
					index	sheet		

Mouser Electronics

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